LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司



WEB: http://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

MODULE NO.:	WO12864I	I-TMI#
APPROVED BY: (FOR CUSTOMER USE ONLY)	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
С	2014/07/17		Modify pull tape.

Winstar Display Co., LTD MODLE NO: 華凌光電股份有限公司

REC	ORDS OF REV	/ISION	DOC. FIRST ISSUE
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2012/01/31		First issue
A	2013/05/27		Modify B/L information
В	2013/10/31		Add Pull Tape
C	2014/07/17		Modify pull tape.

Contents

- 1. Module Classification Information
- 2. Precautions in use of LCD Modules
- 3. General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13.Recommendable Storage

1. Module Classification Information

W	<u>O</u>	12864	<u>H</u>	_	<u>T</u>	<u>M</u>	Ī	_	<u>#</u>
①	2	3	4		(5)	6	7		8

- ① Brand: WINSTAR DISPLAY CORPORATION
- ② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type
- ③ Display Font: 128 * 64 dot
- Model serials no.
- \bigcirc Backlight Type: N \rightarrow Without backlight T \rightarrow LED, White S \rightarrow LED, High light White

 $B \rightarrow EL$, Blue green $A \rightarrow LED$, Amber $L \rightarrow LED$, Full color $D \rightarrow EL$, Green $R \rightarrow LED$, Red $J \rightarrow DIP$ LED, Blue $W \rightarrow EL$, White $O \rightarrow LED$, Orange $K \rightarrow DIP$ LED, White

 $M\rightarrow EL$, Yellow Green $G\rightarrow LED$, Green $E\rightarrow DIP$ LED, Yellow Green

F \rightarrow CCFL, White P \rightarrow LED, Blue H \rightarrow DIP LED, Amber Y \rightarrow LED, Yellow Green X \rightarrow LED, Dual color I \rightarrow DIP LED, Red

 $G \rightarrow LED$, Green $C \rightarrow LED$, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$ Positive, Gray $F \rightarrow FSTN$ Positive $I \rightarrow HTN$ Negative, Black $K \rightarrow FSC$ Negative $U \rightarrow HTN$ Negative, Blue $S \rightarrow FSC$ Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00 E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code #:Fit in with the ROHS Directions and regulations

2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)

3.General Specification

Item	Dimension	Unit			
Number of dots	128 x 64	_			
Module dimension	80.0 x 54.0 x 9.5	mm			
View area	70.7 x 38.8	mm			
Active area	66.52 x 33.24	mm			
Dot size	0.48 x 0.48	mm			
Dot pitch	0.52 x 0.52	mm			
LCD type	STN Negative, Blue Transmissive (In LCD production, It will occur slightly color difference. We can only guarantee the same color in the same batch.)				
Duty	1/65 , 1/9 Bias				
View direction	6 o'clock				
Backlight Type	LED, White				
IC	ST7567-G				

4. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	Vı	-0.3	_	V _{DD} +0.3	V
Digital Power Supply Voltage	V _{DD} -Vss	-0.3	_	3.6	V
LCD Power supply voltage	V0-XV0	-0.3	_	16	V

5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	3.0	3.3	3.6	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	XV0-V0	Ta=25°C	_	10.0	_	V
		Ta=70°C	_	_	_	V
Input High Volt.	$ m V_{IH}$	_	$0.7V_{DD}$	_	$V_{ m DD}$	V
Input Low Volt.	V_{IL}	_	Vss	_	$0.3V_{DD}$	V
Output High Volt.	$ m V_{OH}$	_	$0.8~\mathrm{V_{DD}}$	_	V_{DD}	V
Output Low Volt.	V_{OL}	_	Vss	_	$0.2V_{\mathrm{DD}}$	V
Supply Current(No include LED Backlight)	I_{DD}	V _{DD} =3.3V	_	2.0	_	mA

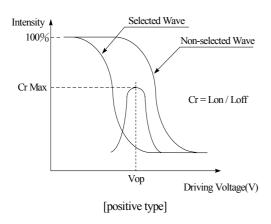
Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

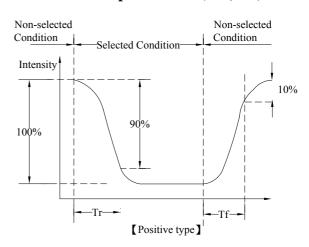
6.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	$\phi = 180^{\circ}$
V: A1-	θ	CR≥2	0	_	40	$\phi = 0^{\circ}$
View Angle	θ	CR≧2	0	_	30	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	30	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_	_	150	200	ms
	T fall	_	_	150	200	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)





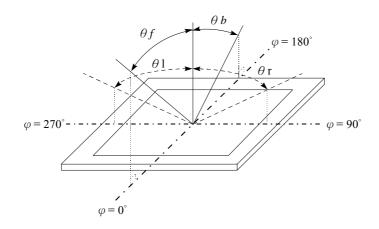
Conditions:

Operating Voltage : Vop

Viewing Angle(θ , φ): 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle($CR \ge 2$)



7.Interface Pin Function

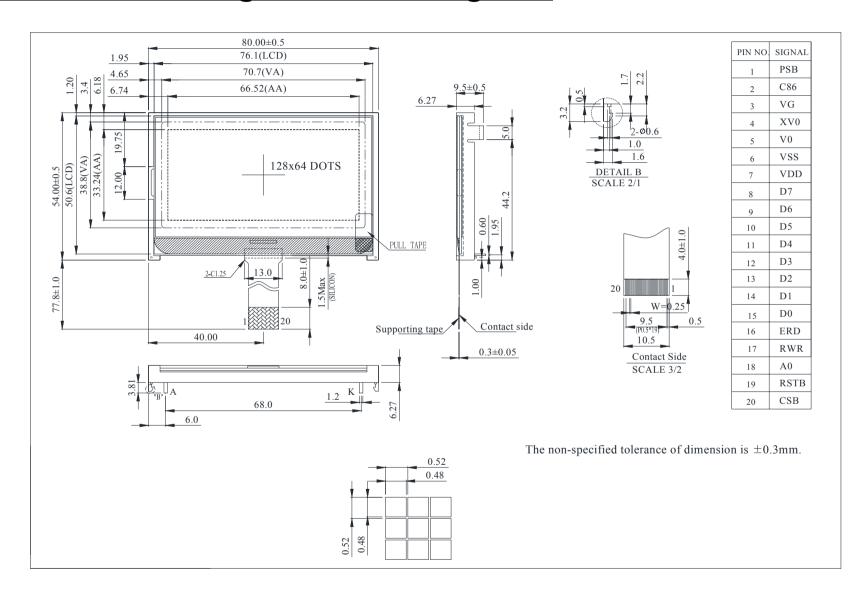
Pin No.	Symbol	Level	Description				
1	PSB	I	PSB select	s the interf	ace type: Serial or Parallel.		
			C86 select	C86 selects the microprocessor type in parallel into			
			PSB	C86	Selected Interface		
			"H"	"H"	Parallel 6800 Series MPU		
			11	11	Interface		
2	C86	I	"H"	"L"	Parallel 8080 Series MPU		
	200	1			Interface		
			"L"	"X"	Serial 4-Line SPI Interface		
					LICATION NOTES" and		
				cessor Inte			
			<u> </u>		ed connection of the selected interface.		
3	VG	Power	VG is the	LCD drivir	ng voltage for segment circuits.		
4	XV0	Power			ing voltage for common circuits at		
			positive fra				
5	V0	Power	V0 is the LCD driving voltage for common circuits at negativ				
_			frame.				
6	VSS				connected to the system GND.		
7	VDD		Shared wit	th the MPU	power supply terminal VDD. (3.3 V)		
8	D7			•	rallel interface: (6800 or 8080 mode)		
9	D6				ata bus. Connect to the data bus of 8-bit		
10	D5		microproce		(CCD (ATA) DEZ 01		
11	D4				tive (CSB="H"), D[7:0] pins are high		
12	D3		impedance When usin		nterface: 4-LINE		
13	D2			O			
14	D1		D7=SDA : Serial data input. D6=SCL : Serial clock input.				
11			D[5:0] are not used and should connect to "H" by VDD1 or				
	VDDH.		-				
15	D0		When CSB is non-active (CSB="H"), D[7:0] pins are high				
			impedance				

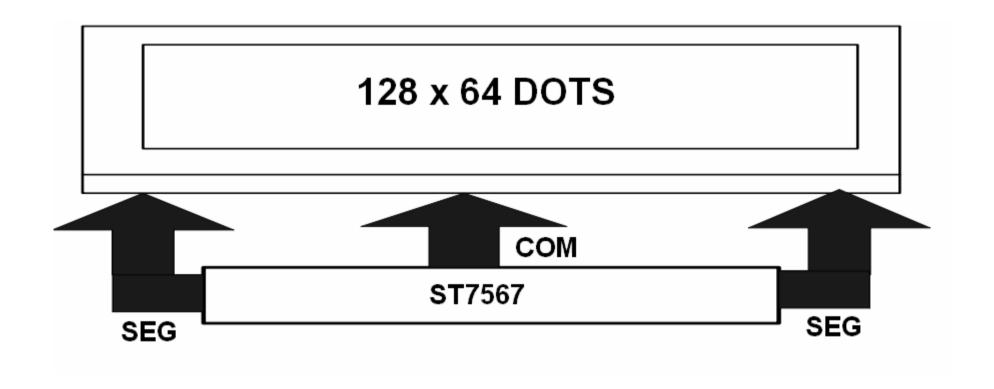
			Read/Write execution control pin. When PSB is "H",						
			C86	MPU Type	ERD	Description			
16	16 ERD I	н	6800 series	E	Read/Write control input pin. R/W="H": When E is "H", D[7:0] are in output mode. R/W="L": Signals on D[7:0] are latched at the falling edge of E signal.				
			L	8080 series	/RD	Read enable input pin. When /RD is "L", D[7:0] are in output mode.			
			VDD	1 or VDD	rial interface and should fix to "H" by control pin. When PSB is "H",				
			C86	MPU Type	RWR	Description			
	17 RWR I		Н	6800 series	RW	Read/Write control input pin. R/W="H": read. R/W="L": write.			
17		1	1	1	I	I	L	8080 series	MR
			RWR is not used in serial interface and should fix to "H" by VDD1 or VDDH.						
			It det		hether	the access is related to data or			
18	A0	I				at signals on D[7:0] are display data.			
			+			at signals on D[7:0] are command.			
19	RSTB	I	Hardware reset input pin. When RSTB is "L", internal initialization is executed						
			and the internal registers will be initialized.						
20	CCD	т	_	•	-	Interface access is enabled when CSB is			
20	CSB	I	"L".When CSB is non-active (CSB="H"), D[7:0] pins are l impedance.						

C1=C2=1UF/0805

CI C	2-10F/(7602
PIN NO.	SIGNAL	
1	PSB	P3.6
2	C86	P3.6
3	VG	
4	XV0	C2 T T C1
5	V0	
6	VSS	VSS
7	VDD	VDD
8	D7	P1.7
9	D6	P1.6
10	D5	P1.5
11	D4	P1.4
12	D3	P1.3
13	D2	P1.2
14	D1	P1.1
15	D0	P1.0
16	ERD	P3.4
17	RWR	P3.7
18	A0	P3.0
19	RSTB	P3.2
20	CSB	P3.3

8.Contour Drawing & Block Diagram





9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test					
Test Item	Content of Test	Test Condition	Note		
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2		
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2		
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs			
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1		
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2		
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles			
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3		
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5k Ω CS=100pF 1 time			

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

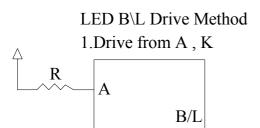
10.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	96	120	mA	V=3.5V
Supply Voltage	v	3.3	3.5	3.7	v	_
Reverse Voltage	VR	_	_	5	v	_
Luminance (Without LCD)	IV	840	1050	_	CD/M ²	ILED=96mA
LED Life Time (For Reference only)	_	_	50K	_	Hr.	ILED=96mA 25°C,50-60%RH, (Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



K

11.Inspection specification

NO	Item	Criterion				AQL	
		Missing vertical	l, horizont	al segment, segment	nt contrast defect.		
	Electrical	Missing character, dot or icon. Display malfunction. No function or no display.					
01	Testing	Current consumption exceeds product specifications. LCD viewing angle defect. Mixed product types. Contrast defect.					
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 				2.5	
		3.1 Round type	: As follo				
		$\Phi = (x + y) / 2$	_	SIZE	Acceptable Q TY		
		→ X ←	↓	$\Phi \leq 0.10$	Accept no dense	2.5	
			<u> </u>	$0.10 < \Phi \le 0.20$	2		
	LCD black		↑	$0.20 < \Phi \le 0.25$	1		
	spots, white spots, contamination		L	0.25<Φ	0		
03		3.2 Line type : (As follow	ving drawing)			
	(non-display)		Length	Width	Acceptable Q TY		
	(non display)	~ /¥w		W≦0.02	Accept no dense		
		→ I I +	L≦3.0	$0.02 < W \le 0.03$	2	2.5	
			L≦2.5	$0.03 < W \le 0.05$	2	2.0	
				0.05 < W	As round type		
				G: *	11 0 777		
		If bubbles are v			Size Φ	Acceptable Q TY	
0.4	Polarizer	judge using blac	_	$\Phi \le 0.20$	Accept no dense	2.5	
04	bubbles	specifications, n	•	$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	2	2.5	
		to find, must che specify direction		$0.30 < \Phi \le 1.00$ $1.00 < \Phi$	0		
		specify diffection	11,	Total Q TY	3		
				10ta1 Q 1 1	J		

NO	Item	Criterion					
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
		Symbols Define:					
		x: Chip length y	: Chip width z: Ch	nip thickness			
		k: Seal width t:	Glass thickness a: LC	CD side length			
		L: Electrode pad length	1:				
		6.1 General glass chip					
		6.1.1 Chip on panel sur	face and crack between	panels:			
		z: Chip thickness	y: Chip width	x: Chip length			
		Z≦1/2t	Not over viewing	x ≤ 1/8a			
06	Chipped		area		2.5		
	glass	$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a			
		6.1.2 Corner crack:	e chips, x is total length	of each chip.			
		z: Chip thickness	y: Chip width	x: Chip length			
		Z≦1/2t	Not over viewing area	x≤1/8a			
		$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a			
		⊙ If there are 2 or more	e chips, x is the total len	gth of each chip.			

NO	Item	Criterion			AQL	
06			s thickness a: LCD	thickness side length		
			1/8a	z: Chip thickness $0 < z \le t$		
	Glass	y X	Z V	1 Z	2.5	
		y: Chip width	x: Chip length	z: Chip thickness		
İ			x ≤ 1/8a	$0 < z \le t$		
		 ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width y: length y y /ul>				

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB	2.5 2.5 0.65 2.5 0.65 2.5 2.5 2.5 2.5 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to sever.	
	Camaral	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12	General	component) is not burned into brown or black color.	
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

12.Material List of Components for

RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS						

2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp.:

Reflow: 250° C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : $235\pm5^{\circ}$ C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

13.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

		Feedback Sheet	
odule Number :			Page: 1
1 Panel Specification:	☐ Pass		
 Panel Type : View Direction : 			
	☐ Pass		
	☐ Pass☐ Pass		
	☐ Pass		
	☐ Pass		
6. Operating Temperature :7. Storage Temperature :	☐ Pass		
8. Others:			
2 · Mechanical Specification :			_
1. PCB Size:	☐ Pass	☐ NG ,	
2. Frame Size:	☐ Pass		
3. Materal of Frame:	Pass		
4. Connector Position:	Pass	□ NG ,	
5. Fix Hole Position:	Pass		
6. Backlight Position:	Pass	□ NG ,	
7. Thickness of PCB:	Pass	□ NG ,	
8. Height of Frame to PCB:	Pass	□ NG ,	
9. Height of Module:	Pass	□ NG ,	
10. Others:	Pass	□ NG ,	
3 · <u>Relative Hole Size</u> :			
1. Pitch of Connector:	Pass	☐ NG ,	
2. Hole size of Connector:	Pass	☐ NG ,	
3. Mounting Hole size:	Pass	☐ NG ,	
4. Mounting Hole Type:	Pass	☐ NG ,	
5. Others:	Pass	☐ NG ,	
4 · Backlight Specification :			
1. B/L Type:	☐ Pass	☐ NG ,	
2. B/L Color:	Pass	☐ NG ,	
3. B/L Driving Voltage (Refere	ence for LED	Гуре): Pass	□ NG ,
4. B/L Driving Current:	Pass	☐ NG ,	
5. Brightness of B/L:	Pass	☐ NG ,	
6. B/L Solder Method:	Pass	☐ NG ,	
7. Others:	Pass	☐ NG ,	



	winstar				
Modu	lle Number:		Page: 2		
5、	Electronic Characteristics of				
1.	Input Voltage:	Pass	□ NG ,		
2.	Supply Current:	Pass	□ NG ,		
3.	Driving Voltage for LCD:	Pass	□ NG ,		
4.	Contrast for LCD:	Pass	□ NG ,		
5.	B/L Driving Method:	Pass	☐ NG ,		
6.	Negative Voltage Output:	Pass	□ NG ,		
7.	Interface Function:	Pass	□ NG ,		
8.	LCD Uniformity:	Pass	☐ NG ,		
9.	ESD test:	Pass	☐ NG ,		
10.	Others:	Pass	□ NG ,		
6、	Summary :				
	Sales signature :				
	Customer Signature:		Date: / /		